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EIA STANDARD

Resistors, Thick Film Resistor Array on Ceramic

EIA-886-B (Revision of EIA-886-A)

August 2020



Electronic Components Industry Association

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Contents

1	Introduction	1
2	Applicable documents (latest version)	1
3	Requirements	1
3.1	Physical.....	1
3.1.1	Dimensions.....	1
3.1.2	Termination style	1
3.1.3	Material.....	2
3.1.4	Solderability.....	2
3.1.5	Solder pad dimensions.....	2
3.1.6	Marking	2
3.2	Electrical	2
3.2.1	Resistor ratings.....	2
3.3	Environmental & mechanical tests.....	3
3.3.1	Resistance to soldering heat	3
3.3.2	Terminal strength	3
3.3.3	Terminal adhesion	3
3.3.4	Thermal shock.....	3
3.3.5	Low temperature operation	3
3.3.6	High temperature exposure	4
3.3.7	Short time overload.....	4
3.3.8	Moisture resistance	4
3.3.9	Life.....	4
3.3.10	Temperature cycling.....	4
3.3.11	Resistance to atmospheric sulfur.....	4
3.3.12	Post environmental & mechanical conditioning	4
3.3.13	Acceptance criteria for environmental & mechanical tests	4
4	Quality Assurance Provisions.....	4
5	Packaging	5

Table 1 - Resistor wattage & voltage..... 2
Table 2 - Dimensions (Isolated arrays only) 5
Table 3 - Dimension (bussed arrays only)..... 6
Table 4 - Solder Pad Figure Dimensions..... 7

Figure 1 - Termination configurations..... 7
Figure 2 - Termination styles 7
Figure 3 - Available circuits..... 8